

AMENDMENTS TO THE Specification

1. Bridging on pages 12 and 13, starting on line 6, please replace with the following paragraphs:

FIG. 1, consisting of FIGS. 1(a) to 1(f), is a flowchart showing an example of an order of steps in a first aspect of a method for manufacturing an SOI wafer of the present invention together with schematic views.

FIG. 2, consisting of FIGS. 2(a), including 2(a-1) and 2(a-2), to 2(f), is a flowchart showing an example of an order of steps in a second aspect of a method for manufacturing an SOI wafer of the present invention together with schematic views.

FIG. 3 is a microscopic photograph showing an example of a line defect on a surface of a bond wafer observed by using a laser microscope with a confocal optical system in Experimental Example 1.

FIG. 4 is a microscopic photograph showing an example of a void on a surface of an SOI wafer observed by using a laser microscope with a confocal optical system in Experimental Example 1.

FIG. 5, consisting of FIGS. 5(a) to 5(f), is a flowchart showing an order of steps in a manufacturing process for an SOI wafer together with schematic views in Experimental Example 1.

FIG. 6, consisting of FIGS. 6(a) and 6(b), is an explanatory view showing an example of manufacture of an SOI wafer, wherein the part (a) is an explanatory plan view and the part (b) is an explanatory sectional view.

FIG. 7, consisting of FIGS. 7(a) to 7(f), is a flowchart showing an example of an order of steps in a conventional general method for manufacturing an SOI wafer together with schematic views.